



ENGLISH

## Datasheet

# Processing Chemical for Tin Plating in Crystals

RS Stock number [567-812](#)



### Features

A unique stable immerse tin powder that although dissolved in water at 50°C, it actually plates at room temperature. The tin molecules deposited at room temperature are very small making the coating fine, hard and homogenous.

### Description

These crystals produce a bright plated finish PCB track and other copper alloys. The plating provides a highly solderable keying surface. Deposition rates of tin to tin of 1.5 to 2.0 microns in the first half hour and 3 to 4 microns in up to 2 hours can be achieved at an optimum room temperature. 5 litres of solution can be made by dissolving the crystals in water at 50°C, which is sufficient to cover 2.7m<sup>2</sup> of board. Instruction leaflet supplied.



**Professionally approved products.**

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### Usage

Firstly it is important that the copper is perfectly clean and free from oxidisation. After the photoresist has been stripped from the circuit and it has been washed and dried it should be scrubbed clean with a PC182 scrubbing block (part no. 900-009). Then bang the board and rub with a hard clean cloth to remove any particles left by the scrubbing block and immediately immerse in the tin.

With fresh solution, after 20 seconds a coating of 0.2 microns will be plated, 0.8-1.0 microns after 5 minutes and 4-5 microns after 3 hours. When the initial area of copper has been plated the tin will begin to plate tin on tin. It is therefore uneconomical to leave a board immersed for too long, overnight for instance.

For optimum results the board should be immersed in cold water as soon as it is removed from the tin. This will stop the tinning process, the board should then be washed in hot water (40°C+) and rubbed dry with a clean cloth before air drying with a hair dryer or other hot air blower.

### Capacity and Shelf Life

1 litre of fresh solution will plate 30-40 complete copper Eurocards with 1-1.5 microns of tin or 10 Eurocards with 5 microns. As an average etched circuit has 30% copper a figure of 100-135 Eurocards respectively is a more accurate figure. The solution will have up to six months shelf life if used in a process tank.